# Abstracts

## Microwave Module Interconnection and Packaging Using Multilayer Thin Film/Thick Film Technology

*A.K. Agrawal, R.D. Clark, J.J. Komiak and R. Browne. "Microwave Module Interconnection and Packaging Using Multilayer Thin Film/Thick Film Technology." 1992 MTT-S International Microwave Symposium Digest 92.3 (1992 Vol. III [MWSYM]): 1509-1511.*

This paper describes a multichip T/R module packaging technique that combines thin film and multilayer thick film metalizations on a single alumina substrate with ceramic seal ring technology to provide a high density, wide bandwidth, high performance package.

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